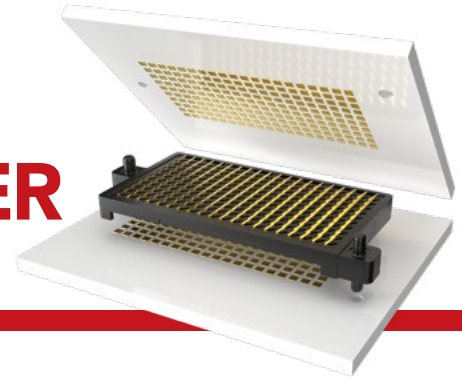


PAM 4

56
G b p s



LOW-PROFILE COMPRESSION INTERPOSER

(1.00 mm) .0394" PITCH • GMI SERIES

SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or 50 μ" (1.27 μm) Ni
Current Rating:
.89 A per pin
(10 pins powered)

GMI

**POSITIONS
PER ROW**

-10, -20, -30

STYLE

-2
= Dual
Compression

**BOARD
SPACING**

-1.27
= (1.27 mm) .050"
Board Space

**PLATING
OPTION**

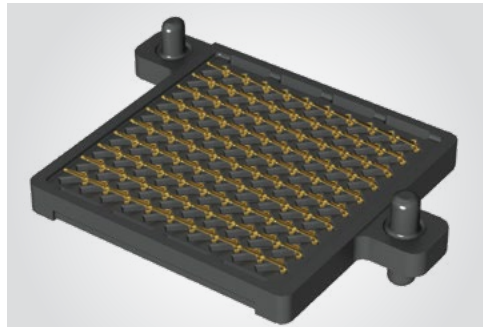
-G
= 10 μ"
(0.25 μm)
Gold on
contact area

ROWS

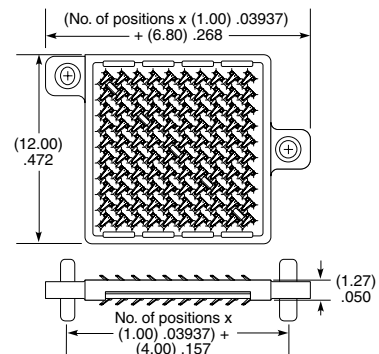
-10
= Ten Rows

PROCESSING

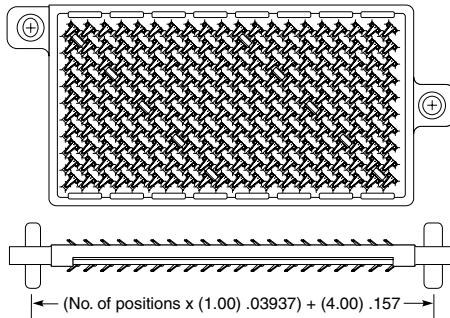
Lead-Free Solderable:
Yes
SMT Lead Complanarity:
(0.05 mm) .002" (10-20)*
(0.08 mm) .003" (30)*
*(.004" stencil solution
may be available;
contact ipg@samtec.com)



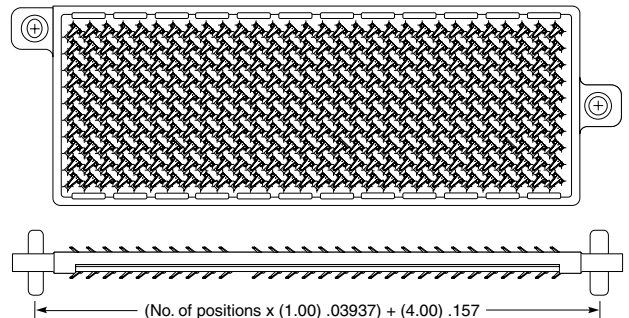
GMI Series is an ideal low-cost solution
for board stacking, module-to-board or
LGA interface



10 X 10



20 X 10



30 X 10

Notes:
Some lengths, styles and options
are non-standard, non-returnable